# E·XFL



#### Welcome to E-XFL.COM

#### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Obsolete
Core Processor	HC11
Core Size	8-Bit
Speed	3MHz
Connectivity	SCI, SPI
Peripherals	POR, WDT
Number of I/O	38
Program Memory Size	-
Program Memory Type	ROMIess
EEPROM Size	512 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	52-LCC (J-Lead)
Supplier Device Package	52-PLCC (19.1x19.1)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc68hc11e1mfne3

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



**Revision History** 

## **Revision History**

Date	Revision Level	Description	Page Number(s)
May 2001	0.1	2.3.3.1 System Configuration Register — Addition to NOCOP bit description	44
iviay, 2001	3.1	Added 10.21 EPROM Characteristics	175
June, 2001	3.2	10.21 EPROM Characteristics — For clarity, addition to note 2 following the table	175
December, 2001	3.3	7.7.2 Serial Communications Control Register 1 — SCCR1 bit 4 (M) description corrected	110
		10.7 MC68L11E9/E20 DC Electrical Characteristics — Title changed to include the MC68L11E20	153
July, 2002	4	10.8 MC68L11E9/E20 Supply Currents and Power Dissipation — Title changed to include the MC68L11E20	154
		10.10 MC68L11E9/E20 Control Timing — Title changed to include the MC68L11E20	157
		10.12 MC68L11E9/E20 Peripheral Port Timing — Title changed to include the MC68L11E20	163
		10.14 MC68L11E9/E20 Analog-to-Digital Converter Characteristics — Title changed to include the MC68L11E20	167
		10.16 MC68L11E9/E20 Expansion Bus Timing Characteristics — Title changed to include the MC68L11E20	169
		10.18 MC68L11E9/E20 Serial Peirpheral Interface Characteristics — Title changed to include the MC68L11E20	172
		— Title changed to include the MC68L11E20	175
		11.4 Extended Voltage Device Ordering Information (3.0 Vdc to 5.5 Vdc) — Updated table to include MC68L1120	181
	5	Format updated to current publications standards	Throughout
June, 2003		1.4.6 Non-Maskable Interrupt (XIRQ/VPPE) — Added Caution note pertaining to EPROM programming of the MC68HC711E9 device only.	23
		6.4 Port C — Clarified description of DDRC[7:0] bits	100
		10.21 EPROM Characteristics — Added note pertaining to EPROM programming of the MC68HC711E9 device only.	175
July, 2005	5.1	Updated to meet Freescale identity guidelines.	Throughout



#### General Description

- Computer operating properly (COP) watchdog system
- 38 general-purpose input/output (I/O) pins:
  - 16 bidirectional I/O pins
  - 11 input-only pins
  - 11 output-only pins
- Several packaging options:
  - 52-pin plastic-leaded chip carrier (PLCC)
  - 52-pin windowed ceramic leaded chip carrier (CLCC)
  - 52-pin plastic thin quad flat pack, 10 mm x 10 mm (TQFP)
  - 64-pin quad flat pack (QFP)
  - 48-pin plastic dual in-line package (DIP), MC68HC811E2 only
  - 56-pin plastic shrink dual in-line package, .070-inch lead spacing (SDIP)

## 1.3 Structure

See Figure 1-1 for a functional diagram of the E-series MCUs. Differences among devices are noted in the table accompanying Figure 1-1.

## **1.4 Pin Descriptions**

M68HC11 E-series MCUs are available packaged in:

- 52-pin plastic-leaded chip carrier (PLCC)
- 52-pin windowed ceramic leaded chip carrier (CLCC)
- 52-pin plastic thin quad flat pack, 10 mm x 10 mm (TQFP)
- 64-pin quad flat pack (QFP)
- 48-pin plastic dual in-line package (DIP), MC68HC811E2 only
- 56-pin plastic shrink dual in-line package, .070-inch lead spacing (SDIP)

Most pins on these MCUs serve two or more functions, as described in the following paragraphs. Refer to Figure 1-2, Figure 1-3, Figure 1-4, Figure 1-5, and Figure 1-6 which show the M68HC11 E-series pin assignments for the PLCC/CLCC, QFP, TQFP, SDIP, and DIP packages.



General Description

## NOTE

IRQ must be configured for level-sensitive operation if there is more than one source of IRQ interrupt.

There should be a single pullup resistor near the MCU interrupt input pin (typically 4.7 k $\Omega$ ). There must also be an interlock mechanism at each interrupt source so that the source holds the interrupt line low until the MCU recognizes and acknowledges the interrupt request. If one or more interrupt sources are still pending after the MCU services a request, the interrupt line will still be held low and the MCU will be interrupted again as soon as the interrupt mask bit in the MCU is cleared (normally upon return from an interrupt). Refer to Chapter 5 Resets and Interrupts.

 $V_{PPE}$  is the input for the 12-volt nominal programming voltage required for EPROM/OTPROM programming. On devices without EPROM/OTPROM, this pin is only an XIRQ input.

### CAUTION

During EPROM programming of the MC68HC711E9 device, the V<sub>PPE</sub> pin circuitry may latch-up and be damaged if the input current is not limited to 10 mA. For more information please refer to MC68HC711E9 8-Bit Microcontroller Unit Mask Set Errata 3 (Freescale document order number 68HC711E9MSE3.

## 1.4.7 MODA and MODB (MODA/LIR and MODB/V<sub>STBY</sub>)

During reset, MODA and MODB select one of the four operating modes:

- Single-chip mode
- Expanded mode
- Test mode
- Bootstrap mode

Refer to Chapter 2 Operating Modes and On-Chip Memory.

After the operating mode has been selected, the load instruction register ( $\overline{\text{LIR}}$ ) pin provides an open-drain output to indicate that execution of an instruction has begun. A series of E-clock cycles occurs during execution of each instruction. The  $\overline{\text{LIR}}$  signal goes low during the first E-clock cycle of each instruction (opcode fetch). This output is provided for assistance in program debugging.

The V<sub>STBY</sub> pin is used to input random-access memory (RAM) standby power. When the voltage on this pin is more than one MOS threshold (about 0.7 volts) above the V<sub>DD</sub> voltage, the internal RAM and part of the reset logic are powered from this signal rather than the V<sub>DD</sub> input. This allows RAM contents to be retained without V<sub>DD</sub> power applied to the MCU. Reset must be driven low before V<sub>DD</sub> is removed and must remain low until V<sub>DD</sub> has been restored to a valid level.

## 1.4.8 $V_{RL}$ and $V_{RH}$

These two inputs provide the reference voltages for the analog-to-digital (A/D) converter circuitry:

- V<sub>RL</sub> is the low reference, typically 0 Vdc.
- V<sub>RH</sub> is the high reference.

For proper A/D converter operation:

- V<sub>RH</sub> should be at least 3 Vdc greater than V<sub>RL</sub>.
- $V_{RL}$  and  $V_{RH}$  should be between  $V_{SS}$  and  $V_{DD}$ .











M68HC11E Family Data Sheet, Rev. 5.1

# NP

#### **Operating Modes and On-Chip Memory**

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0		
\$1000	Port A Data Register (PORTA)	Read: Write:	PA7	PA6	PA5	PA4	PA3	PA2	PA1	PA0		
	See page 98.	Reset:	I	0	0	0	Ι	I	Ι	Ι		
\$1001	Reserved		R	R	R	R	R	R	R	R		
					•	•						
\$1002	Parallel I/O Control Register (PIOC)	Read: Write:	STAF	STAI	CWOM	HNDS	OIN	PLS	EGA	INVB		
	See page 102.	Reset:	0	0	0	0	0	U	1	1		
\$1003	Port C Data Register (PORTC)	Read: Write:	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0		
	See page 99.	Reset:		Indeterminate after reset								
\$1004	Port B Data Register (PORTB)	Read: Write:	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0		
	See page 99.	Reset:	0	0	0	0	0	0	0	0		
\$1005	Port C Latched Register (PORTCL)	Read: Write:	PCL7	PCL6	PCL5	PCL4	PCL3	PCL2	PCL1	PCL0		
	See page 99.	Reset:	Indeterminate after reset									
\$1006	Reserved		R	R	R	R	R	R	R	R		
						-			-			
\$1007	Port C Data Direction Register (DDRC)	Read: Write:	DDRC7	DDRC6	DDRC5	DDRC4	DDRC3	DDRC2	DDRC1	DDRC0		
	See page 100.	Reset:	0	0	0	0	0	0	0	0		
\$1008	Port D Data Register (PORTD)	Read: Write:	0	0	PD5	PD4	PD3	PD2	PD1	PD0		
	See page 100.	Reset:	U	U	1	I	I	Ι	I	I		
\$1009	Port D Data Direction Register (DDRD)	Read: Write:			DDRD5	DDRD4	DDRD3	DDRD2	DDRD1	DDRD0		
	See page 100.	Reset:	0	0	0	0	0	0	0	0		
\$100A	Port E Data Register (PORTE)	Read: Write:	PE7	PE6	PE5	PE4	PE3	PE2	PE1	PE0		
	See page 101.	Reset:	Indeterminate after reset									
\$100B	Timer Compare Force Register (CFORC)	Read: Write:	FOC1	FOC2	FOC3	FOC4	FOC5					
	See page 135.	Reset:	0	0	0	0	0	0	0	0		
\$100C	Output Compare 1 Mask Register (OC1M)	Read: Write:	OC1M7	OC1M6	OC1M5	OC1M4	OC1M3					
	See page 136.	Reset:	0	0	0	0	0	0	0	0		
				= Unimplen	nented	R	= Reserved U = Unaffected					
		I = Indeterminate after reset										

Figure 2-7. Register and Control Bit Assignments (Sheet 1 of 6)

M68HC11E Family Data Sheet, Rev. 5.1



#### PGM — EPROM Programming Voltage Enable Bit

PGM can be read any time and can be written only when ELAT = 1.

- 0 = Programming voltage to EPROM array disconnected
- 1 = Programming voltage to EPROM array connected

## 2.5 EEPROM

Some E-series devices contain 512 bytes of on-chip EEPROM. The MC68HC811E2 contains 2048 bytes of EEPROM with selectable base address. All E-series devices contain the EEPROM-based CONFIG register.

## 2.5.1 EEPROM and CONFIG Programming and Erasure

The erased state of an EEPROM bit is 1. During a read operation, bit lines are precharged to 1. The floating gate devices of programmed bits conduct and pull the bit lines to 0. Unprogrammed bits remain at the precharged level and are read as ones. Programming a bit to 1 causes no change. Programming a bit to 0 changes the bit so that subsequent reads return 0.

When appropriate bits in the BPROT register are cleared, the PPROG register controls programming and erasing the EEPROM. The PPROG register can be read or written at any time, but logic enforces defined programming and erasing sequences to prevent unintentional changes to EEPROM data. When the EELAT bit in the PPROG register is cleared, the EEPROM can be read as if it were a ROM.

The on-chip charge pump that generates the EEPROM programming voltage from  $V_{DD}$  uses MOS capacitors, which are relatively small in value. The efficiency of this charge pump and its drive capability are affected by the level of  $V_{DD}$  and the frequency of the driving clock. The load depends on the number of bits being programmed or erased and capacitances in the EEPROM array.

The clock source driving the charge pump is software selectable. When the clock select (CSEL) bit in the OPTION register is 0, the E clock is used; when CSEL is 1, an on-chip resistor-capacitor (RC) oscillator is used.

The EEPROM programming voltage power supply voltage to the EEPROM array is not enabled until there has been a write to PPROG with EELAT set and PGM cleared. This must be followed by a write to a valid EEPROM location or to the CONFIG address, and then a write to PPROG with both the EELAT and EPGM bits set. Any attempt to set both EELAT and EPGM during the same write operation results in neither bit being set.

#### 2.5.1.1 Block Protect Register

This register prevents inadvertent writes to both the CONFIG register and EEPROM. The active bits in this register are initialized to 1 out of reset and can be cleared only during the first 64 E-clock cycles after reset in the normal modes. When these bits are cleared, the associated EEPROM section and the CONFIG register can be programmed or erased. EEPROM is only visible if the EEON bit in the CONFIG register is set. The bits in the BPROT register can be written to 1 at any time to protect EEPROM and the CONFIG register. In test or bootstrap modes, write protection is inhibited and BPROT can be written repeatedly. Address ranges for protected areas of EEPROM differ significantly for the MC68HC811E2. Refer to Figure 2-16.



**Operating Modes and On-Chip Memory** 



**Central Processor Unit (CPU)** 

## 4.2.1 Accumulators A, B, and D

Accumulators A and B are general-purpose 8-bit registers that hold operands and results of arithmetic calculations or data manipulations. For some instructions, these two accumulators are treated as a single double-byte (16-bit) accumulator called accumulator D. Although most instructions can use accumulators A or B interchangeably, these exceptions apply:

- The ABX and ABY instructions add the contents of 8-bit accumulator B to the contents of 16-bit register X or Y, but there are no equivalent instructions that use A instead of B.
- The TAP and TPA instructions transfer data from accumulator A to the condition code register or from the condition code register to accumulator A. However, there are no equivalent instructions that use B rather than A.
- The decimal adjust accumulator A (DAA) instruction is used after binary-coded decimal (BCD) arithmetic operations, but there is no equivalent BCD instruction to adjust accumulator B.
- The add, subtract, and compare instructions associated with both A and B (ABA, SBA, and CBA) only operate in one direction, making it important to plan ahead to ensure that the correct operand is in the correct accumulator.

## 4.2.2 Index Register X (IX)

The IX register provides a 16-bit indexing value that can be added to the 8-bit offset provided in an instruction to create an effective address. The IX register can also be used as a counter or as a temporary storage register.

## 4.2.3 Index Register Y (IY)

The 16-bit IY register performs an indexed mode function similar to that of the IX register. However, most instructions using the IY register require an extra byte of machine code and an extra cycle of execution time because of the way the opcode map is implemented. Refer to 4.4 Opcodes and Operands for further information.

## 4.2.4 Stack Pointer (SP)

The M68HC11 CPU has an automatic program stack. This stack can be located anywhere in the address space and can be any size up to the amount of memory available in the system. Normally, the SP is initialized by one of the first instructions in an application program. The stack is configured as a data structure that grows downward from high memory to low memory. Each time a new byte is pushed onto the stack, the SP is decremented. Each time a byte is pulled from the stack, the SP is incremented. At any given time, the SP holds the 16-bit address of the next free location in the stack. Figure 4-2 is a summary of SP operations.

When a subroutine is called by a jump-to-subroutine (JSR) or branch-to- subroutine (BSR) instruction, the address of the instruction after the JSR or BSR is automatically pushed onto the stack, least significant byte first. When the subroutine is finished, a return-from-subroutine (RTS) instruction is executed. The RTS pulls the previously stacked return address from the stack and loads it into the program counter. Execution then continues at this recovered return address.

When an interrupt is recognized, the current instruction finishes normally, the return address (the current value in the program counter) is pushed onto the stack, all of the CPU registers are pushed onto the stack, and execution continues at the address specified by the vector for the interrupt.



## 4.5.3 Extended

In the extended addressing mode, the effective address of the argument is contained in two bytes following the opcode byte. These are 3-byte instructions (or 4-byte instructions if a prebyte is required). One or two bytes are needed for the opcode and two for the effective address.

#### 4.5.4 Indexed

In the indexed addressing mode, an 8-bit unsigned offset contained in the instruction is added to the value contained in an index register (IX or IY). The sum is the effective address. This addressing mode allows referencing any memory location in the 64-Kbyte address space. These are 2- to 5-byte instructions, depending on whether or not a prebyte is required.

### 4.5.5 Inherent

In the inherent addressing mode, all the information necessary to execute the instruction is contained in the opcode. Operations that use only the index registers or accumulators, as well as control instructions with no arguments, are included in this addressing mode. These are 1- or 2-byte instructions.

#### 4.5.6 Relative

The relative addressing mode is used only for branch instructions. If the branch condition is true, an 8-bit signed offset included in the instruction is added to the contents of the program counter to form the effective branch address. Otherwise, control proceeds to the next instruction. These are usually 2-byte instructions.

## 4.6 Instruction Set

Refer to Table 4-2, which shows all the M68HC11 instructions in all possible addressing modes. For each instruction, the table shows the operand construction, the number of machine code bytes, and execution time in CPU E-clock cycles.



**Low-Power Operation** 



Figure 5-5. Processing Flow Out of Reset (Sheet 1 of 2)

M68HC11E Family Data Sheet, Rev. 5.1



#### Serial Communications Interface (SCI)



Note: Refer to Figure B-1. EVBU Schematic Diagram for an example of connecting TxD to a PC.

Figure 7-1. SCI Transmitter Block Diagram



Serial Peripheral Interface (SPI)



#### Timing Systems

input capture register pair inhibits a new capture transfer for one bus cycle. If a double-byte read instruction, such as load double accumulator D (LDD), is used to read the captured value, coherency is assured. When a new input capture occurs immediately after a high-order byte read, transfer is delayed for an additional cycle but the value is not lost.





M68HC11E Family Data Sheet, Rev. 5.1



**Timing Systems** 



## Chapter 10 Electrical Characteristics

## **10.1 Introduction**

This section contains electrical specifications for the M68HC11 E-series devices.

## **10.2 Maximum Ratings for Standard and Extended Voltage Devices**

Maximum ratings are the extreme limits to which the microcontroller unit (MCU) can be exposed without permanently damaging it.

NOTE

This device is not guaranteed to operate properly at the maximum ratings. Refer to 10.5 DC Electrical Characteristics, 10.6 Supply Currents and Power Dissipation, 10.7 MC68L11E9/E20 DC Electrical Characteristics, and 10.8 MC68L11E9/E20 Supply Currents and Power Dissipation for guaranteed operating conditions.

Rating	Symbol	Value	Unit
Supply voltage	V <sub>DD</sub>	-0.3 to +7.0	V
Input voltage	V <sub>In</sub>	-0.3 to +7.0	V
Current drain per pin^{(1)} excluding V_{DD}, V_{SS}, AV_{DD}, V_{RH}, V_{RL}, and $\overline{XIRQ'}V_{PPE}$	Ι <sub>D</sub>	25	mA
Storage temperature	T <sub>STG</sub>	–55 to +150	°C

1. One pin at a time, observing maximum power dissipation limits

## NOTE

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum-rated voltages to this high-impedance circuit. For proper operation, it is recommended that  $V_{In}$  and  $V_{Out}$  be constrained to the range  $V_{SS} \leq (V_{In} \text{ or } V_{Out}) \leq V_{DD}$ . Reliability of operation is enhanced if unused inputs are connected to an appropriate logic voltage level (for example, either  $V_{SS}$  or  $V_{DD}$ ).



MC68L11E9/E20 Supply Currents and Power Dissipation



Notes:

- 1. Full test loads are applied during all dc electrical tests and ac timing measurements.
- 2. During ac timing measurements, inputs are driven to 0.4 volts and  $V_{DD} 0.8$  volts while timing measurements are taken at 20% and 70% of  $V_{DD}$  points.

#### Figure 10-1. Test Methods



#### **Electrical Characteristics**



Note: Measurement points shown are 20% and 70% of  $V_{\text{DD}}.$ 

Figure 10-14. Multiplexed Expansion Bus Timing Diagram



## Appendix B EVBU Schematic

Refer to Figure B-1 for a schematic diagram of the M68HC11EVBU Universal Evaluation Board. This diagram is included for reference only.



Main Bootloader Program



Figure 2. Automatic Detection of Baud Rate

Samples taken at [7] detect the failing edge of the start bit and verify it is a logic 0. Samples taken at the middle of what the receiver interprets as the first five bit times [8] detect logic 0s. The sample taken at the middle of what the receiver interprets as bit 5 [9] may detect either a 0 or a 1 because the receive data has a rising transition at about this time. The samples for bits 6 and 7 detect 1s, causing the receiver to think the received character was \$C0 or \$E0 [10] at 7812 baud instead of the \$FF which was sent at 1200 baud. The stop bit sample detects a 1 as expected [11], but this detection is actually in the middle of bit 0 of the 1200 baud \$FF character. The SCI receiver is not confused by the rest of the 1200 baud \$FF character other than \$FF is sent as the first character, an SCI receive error could result.

#### Main Bootloader Program

Figure 3 is a flowchart of the main bootloader program in the MC68HC711E9. This bootloader demonstrates the most important features of the bootloaders used on all M68HC11 Family members. For complete listings of other M68HC11 versions, refer to Listing 3. MC68HC711E9 Bootloader ROM at the end of this application note, and to **Appendix B** of the *M68HC11 Reference Manual*, Freescale document order number M68HC11RM/AD.

The reset vector in the boot ROM points to the start [1] of this program. The initialization block [2] establishes starting conditions and sets up the SCI and port D. The stack pointer is set because there are push and pull instructions in the bootloader program. The X index register is pointed at the start of the register block (\$1000) so indexed addressing can be used. Indexed addressing takes one less byte of ROM space than extended instructions, and bit manipulation instructions are not available in extended addressing forms. The port D wire-OR mode (DWOM) bit in the serial peripheral interface control register (SPCR) is set to configure port D for wired-OR operation to minimize potential conflicts with external systems that use the PD1/TxD pin as an input. The baud rate for the SCI is initially set to 7812 baud at a 2-MHz E-clock rate but can automatically switch to 1200 baud based on the first character received. The SCI receiver and transmitter are enabled. The receiver is required by the bootloading process, and the transmitter is used to transmit data back to the host computer for optional verification. The last item in the initialization is to set an intercharacter delay constant used to terminate the download when the host computer stops sending data to the MC68HC711E9. This delay constant is stored in the timer output compare 1 (TOC1) register, but the on-chip timer is not used in the bootloader program. The scample

```
NP
```

## Listing 1. MCU-to-MCU Duplicator Program

82	B666											
83	B666	150482	DUNF	PRG	BCLR	PORTB	(RESE	Γ+RED)	Red OI	FF, apply	/ reset	
84	B669	20FE			BRA	*		1	Done so	o just ha	ang	
85	B66B											
86			* * * *	*****	* * * * * * * *	******	******	*****	*****	* * * * * * * * *	*	
87			* Su	* Subroutine to get & send an SCI char. Also								
88			* a	* advances pointer (X).								
89	DCCD	<b>R</b> 6 0 0	****	******	*******	******	*****	*****	******	*******	٢	
90	B66B	A600	SENL			U,X	יח הייים	) ו ת דערתר	Get a ( Weit f	character	<u>-</u>	
91	B66D	132E80FC	IRDI	ШΡ	BRCLR CTTN N	SCSR J	LDRE IF	КЛІГЬР	Walt IC	DI IDRE		
92	D671	972F			JIAA	SCDR			Avance	nainter	<u>^</u>	
94	B674	39			RTS			-	** Reti	rn **	-	
95	D0/1	55			1110				neer	A = 11		
96			* * * *	******	* * * * * * * *	* * * * * * *	******	*****	*****	* * * * * * * * *	*	
97			* Pr	ogram	to be bo	otload	led to	targe	t '711B	E9		
98			****	*****	******	******	*****	*****	*****	*******	ł	
99	B675	8604	BLPR	ROG	LDAA	#\$04			Pattern	n for DWC	OM off, no SP	I
100	B677	B71028			STAA	\$1028			Turns d	off DWOM	in target MC	U
101			* NC	DTE: Cai	n't use	direct	addre	essing	in ta	rget MCU	because	
102			*	reg	gs are l	located	1 at \$1	L000.				
103	B67A	7EBF00			JMP	PROGRA	MA		Jumps t	to EPROM	prog routine	:
104	B67D		ENDE	BPR	EQU	*						
~ .												
Symt	ol Ta	able:	-			- 1	~	<b>D</b> C				
Symb	DOL Na	ame Va	alue	Dei.#	Line I	Number	Cross	Refer	ence			
BEGI	N	1	B600	*00029								
BLLC	)0P	1	B616	*00038	00040							
BLPF	ROG	]	B675	*00099	00037							
DATA	ALP	]	B648	*00068	00079							
DLYI	ΓP	]	B620	*00046	00047							
DLYI	JP2	]	B637	*00059	00063							
DUNE	PRG	]	B666	*00083	00076							
ENDE	BPR	]	B67D	*00104	00039							
EPSI	TRT	]	D000	*00023	00055	00066						
GREE	EN		0001	*00015	00075	00081						
INIJ	ſ		103D	*00009	00029							
PORT	ГВ		0004	*00011	00033	00058	00061	00075	00081	00083		
PORI	ΓE		A000	*00016	00059							
PROC	FRAM	]	BF00	*00022	00103							
RDRE	<b>,</b> '		0020	*00020	00034	00053	00071					
RED			0002	*00014	00058	00061	00075	00083				
RESE	2.T.		0080	*00013	00032	00083	00054	00070	00000			
SCDF				*00021 *00017	00036	00049	00054	00072	00092			
CENI	11	1	BEEB	*00017	00034	00048	000000	00071	00091			
SPUE	) 1		0000	*00010	00030	00007	00070					
TDRF	د ۲		0020	*00019	00091							
TRDY	_ /T.P	1	B66D	*00091	00091							
VERF	 7	1	B64F	*00071	00069	00071						
VERE	FOK	]	B65F	*00078	00074							
WT4E	BRK	]	B60B	*00034	00034							
WT4E	F	1	B627	*00053	00053							
WT4\	/PP	]	B630	*00057	00060							

M68HC11 Bootstrap Mode, Rev. 1.1